EP-Style Mixer Outline

i1 (-1) must be specified if required - i2 (-2) is standard for EP-Carrier catalog mixers

EP Substrate material is 31-mil thick FR4, 1.0 Oz Electrodeposited Cu.
EP I/O castellations and ground plane finish is 100-300 µ-inches 60/40 (approximately) Sn/Pb Solder Plate (IAW MIL-P-81728) over Cu.
Click on links for suggested PCB layout and DXF file.